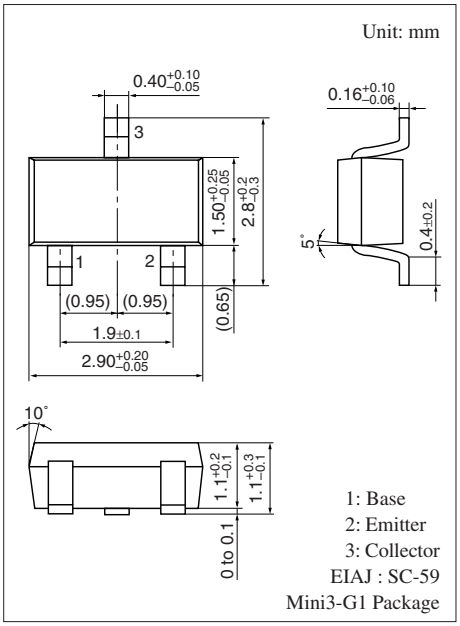
UNR211W

Silicon PNP epitaxial planar type

For digital circuits

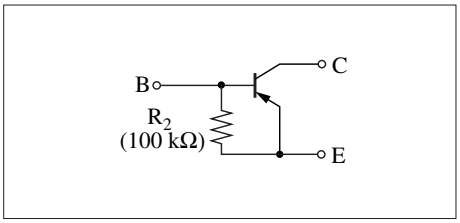
■ Features

- Base-emitter resistance R_{BE}: 100 kΩ,
- Mini type package, allowing downsizing of the sets and automatic insertion through the tape packing



Marking Symbol: 7F

Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	−50	V
Collector-emitter voltage (Base open)	V_{CEO}	−50	V
Collector current	I_C	−100	mA
Total power dissipation	P_T	200	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10$ µA, $I_E = 0$	−50			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2$ mA, $I_B = 0$	−50			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -50$ V, $I_E = 0$			− 0.1	µA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -50$ V, $I_B = 0$			− 0.5	µA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -6$ V, $I_C = 0$			−100	µA
Forward current transfer ratio	h_{FE}	$V_{CE} = -10$ V, $I_C = -5$ mA	80			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -10$ mA, $I_B = -0.3$ mA			− 0.25	V
Input resistance	R_2		−30%	100	+30%	kΩ
Transition frequency	f_T	$V_{CB} = -10$ V, $I_E = 2$ mA, f = 200 MHz		100		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

This product complies with the RoHS Directive (EU 2002/95/EC).

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